



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20260611001.1**  
**Qualification of TIEM as an additional Assembly site for select devices**  
**Change Notification / Sample Request**

**Date:** June 11, 2026  
**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team  
SC Business Services

**20260611001.1**  
**Attachment: 1**




**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

| <b>DEVICE</b>  | <b>CUSTOMER PART NUMBER</b> |
|----------------|-----------------------------|
| TPD1E05U06DPYR | NULL                        |
| TPD1E10B09DPYR | NULL                        |
| TPD1E1B04DPYR  | NULL                        |
| TPD1E0B04DPYR  | NULL                        |
| ESD401DPYR     | NULL                        |
| TPD1E10B06DPYR | NULL                        |
| TPD1E04U04DPYR | NULL                        |
| ESD351DPYR     | NULL                        |
| ESD321DPYR     | NULL                        |
| ESD761DPYR     | NULL                        |

Technical details of this Product Change follow on the next page(s).

|   |   |                                     |  |                                     |                     |
|---|---|-------------------------------------|--|-------------------------------------|---------------------|
| <b>PCN Number:</b>  | 20260611001.1   |                                     |  | <b>PCN Date:</b>                    | June 11, 2026       |
| <b>Title:</b>   | Qualification of TIEM as an additional Assembly site for select devices |                                     |  |                                     |                     |
| <b>Customer Contact:</b>  | Change Management team  |                                     | <b>Dept:</b>                           | Quality Services                    |                     |
| <b>Proposed 1<sup>st</sup> Ship Date:</b>   | September 09, 2026  |                                     | <b>Sample requests accepted until:</b> | August 10, 2026*                    |                     |
| *Sample requests received after August 10, 2026 will not be supported.  |   |                                     |  |                                     |                     |
| <b>Change Type:</b>   |   |                                     |  |                                     |                     |
| <input checked="" type="checkbox"/>   | Assembly Site   | <input type="checkbox"/>            | Design                                 | <input type="checkbox"/>            | Wafer Bump Material |
| <input type="checkbox"/>  | Assembly Process  | <input type="checkbox"/>            | Data Sheet                             | <input type="checkbox"/>            | Wafer Bump Process  |
| <input checked="" type="checkbox"/>   | Assembly Materials  | <input type="checkbox"/>            | Part number change                     | <input type="checkbox"/>            | Wafer Fab Site      |
| <input type="checkbox"/>  | Mechanical Specification  | <input type="checkbox"/>            | Test Site                              | <input type="checkbox"/>            | Wafer Fab Material  |
| <input checked="" type="checkbox"/>   | Packing/Shipping/Labeling   | <input type="checkbox"/>            | Test Process                           | <input type="checkbox"/>            | Wafer Fab Process   |
| <b>PCN Details</b>  |   |                                     |  |                                     |                     |
| <b>Description of Change:</b>   |   |                                     |  |                                     |                     |
| Texas Instruments is pleased to announce the qualification of TIEM as an additional Assembly site for select devices. Material differences between sites as follows.                          |   |                                     |  |                                     |                     |
|   | <b>Current Site</b>   | <b>Additional Site</b>              |  |                                     |                     |
| Assembly site   | CDAT  | TIEM                                |  |                                     |                     |
| Lead finish   | NiPdAu  | Matte Sn                            |  |                                     |                     |
| Qual details are provided in the Qual Data Section.   |   |                                     |  |                                     |                     |
| <b>Reason for Change:</b>   |   |                                     |  |                                     |                     |
| Continuity of Supply  |   |                                     |  |                                     |                     |
| <b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>   |   |                                     |  |                                     |                     |
| Physical aspects of the device have changed. Review the Standard Data Packet for more details on the changes.   |   |                                     |  |                                     |                     |
| <b>Impact on Environmental Ratings</b>  |   |                                     |  |                                     |                     |
| Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. |   |                                     |  |                                     |                     |
|   | <b>RoHS</b>   | <b>REACH</b>                        | <b>Green Status</b>                    | <b>IEC 62474</b>                    |                     |
| <input checked="" type="checkbox"/>   | No Change   | <input checked="" type="checkbox"/> | No Change                              | <input checked="" type="checkbox"/> | No Change           |
| <b>Changes to product identification resulting from this PCN:</b>   |   |                                     |  |                                     |                     |
| <b>Assembly Site Information:</b>   |   |                                     |  |                                     |                     |
| Assembly Site   | Assembly Site Origin (22L)  | Assembly Country Code (23L)         | Assembly City                          |                                     |                     |
| CDAT  | CDA   | CHN                                 | Chengdu                                |                                     |                     |
| TIEM  | CU6   | MYS                                 | Melaka                                 |                                     |                     |
| <b>Sample Product Shipping Label (not actual product label)</b>   |   |                                     |  |                                     |                     |

|   |  |   |  |          |  |  |  |
|---|--|---|--|----------|--|--|--|
| <br><b>TEXAS INSTRUMENTS</b><br>MADE IN: Malaysia<br>2DC: 2Q:    | <br><b>G4</b> |  | (1P) SN74LS07NSR<br>(Q) 2000 (D) 0336<br>(31T) LOT: 3959047MLA<br>(4W) TKY (1T) 7523483SI2<br>(P)<br>(2P) REV: (V) 0033317<br>(20L) CSO: SHE (21L) CCO: USA<br>(22L) ASO: MLA (23L) ACO: MYS |          |  |  |  |
| <table border="1"> <tr> <td>MSL 2 / 260C / 1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C / UNLIM</td> <td>03/29/04</td> </tr> </table> | MSL 2 / 260C / 1 YEAR  | SEAL DT   | MSL 1 / 235C / UNLIM   | 03/29/04 |  |  |  |
| MSL 2 / 260C / 1 YEAR   | SEAL DT  |   |  |          |  |  |  |
| MSL 1 / 235C / UNLIM  | 03/29/04   |   |  |          |  |  |  |
| OPT:<br>ITEM: 39<br><b>LBL: 5A (L)T0:1750</b>   |  |   |  |          |  |  |  |
| <b>Product Affected:</b>  |  |   |  |          |  |  |  |
| ESD321DPYR  | TPD1E04U04DPYR   | TPD1E10B09DPYR  |  |          |  |  |  |
| ESD351DPYR  | TPD1E05U06DPYR   | TPD1E1B04DPYR   |  |          |  |  |  |
| ESD401DPYR  | TPD1E0B04DPYR  |   |  |          |  |  |  |
| ESD761DPYR  | TPD1E10B06DPYR   |   |  |          |  |  |  |

## Qualification Report

### UxQFN TIEM

Approve Date 05-JUNE -2026

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type  | #  | Test Name                     | Condition  | Duration   | Qual Device:<br>ESD761DPYR | QBS Process (Silicon node) Reference:<br>PTPDTESTULCDQAR | QBS Package (UxSON) Reference:<br>LM26LVQISD-130/NOPB |
|-------|----|-------------------------------|--|------------|----------------------------|--|---|
| HAST  | A2 | Biased HAST                   | 130C/85%RH   | 96 Hours   | QBS to LM26LVQISDJ1NC      |  | 3/231/0   |
| UHAST | A3 | Unbiased HAST                 | 130C/85%RH   | 96 Hours   | QBS to LM26LVQISDJ1NC      |  | 3/231/0   |
| TC    | A4 | Temperature Cycle             | -65C/150C  | 500 Cycles | QBS to LM26LVQISDJ1NC      |  | 3/231/0   |
| HTSL  | A6 | High Temperature Storage Life | 170C   | 420 Hours  | QBS to LM26LVQISDJ1NC      |  | 3/231/0   |
| HTOL  | B1 | Life Test                     | 150C   | 300 Hours  | QBS to TPD4E02B05A1        | 3/231/0  | -   |
| WBS   | C1 | Ball Shear                    | 76 balls, 3 units min  | Wires      | QBS to LM26LVQISDJ1NC      |  | 3/228/0   |
| WBP   | C2 | Bond Pull                     | 76 Wires, 3 units min  | Wires      | QBS to LM26LVQISDJ1NC      |  | 3/228/0   |
| SD    | C3 | PB-Free Solderability         | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder; | -          | 1/22/0                     |  | -   |

QBS: Qual By Similarity, also known as Generic Data

Qual Device ESD761DPYR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles  
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>  
TI Qualification ID: R-CHG-2602-099

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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